506837476 08/26/2021

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Hsienshih CHU	12/19/2019
Dehao HUANG	12/19/2019
Yunfan CHOU	12/19/2019
Yaoguang XU	12/19/2019
Yucheng TUNG	12/20/2019

RECEIVING PARTY DATA

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Street Address:	No.88, Lianhua Avenue, Integrated Circuit Science Park, Jinjiang City
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State/Country:	CHINA

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16874694

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SIGNATURE:	/SIBYL YU/
DATE SIGNED:	08/26/2021

Total Attachments: 2 source=np005#page1.tif source=np005#page2.tif

> **PATENT** REEL: 057291 FRAME: 0860

506837476

Attorney Docket No.: PN125876FJJH

ASSIGNMENT

For valuable consideration, WE CHU, Hsienshih, HUANG, Dehao, CHOU, Yunfan; XU,
Yaoguang and TUNG, Yucheng of No.88, Lianhua Avenue, Integrated Circuit Science Park,
Jinjiang City, Quanzhou City, Fujian Province, 362200 China, hereby assign to: Fujian Jinhua
Integrated Circuit Co Ltd, having a place of business at: No.88, Lianhua Avenue, Integrated
Circuit Science Park, Jinjiang City, Quanzhou City, Fujian Province, 362200 China and Its
successors and assigns (collectively hereinafter called "the Assignee") the entire right, title and
interest throughout the world in the inventions and improvements which are the subject of an
application for United States Patent signed by us,
entitled Shallow trench isolating structure and semiconductor device filed
and assigned U.S. Serial Number; this
assignment including said application, (and do hereby authorize ASSIGNEE and its
representative to hereafter add herein such application number(s) and/or filing date(s) when
known), any provisional, non-provisional, continuation, continuation-in-part, divisional, reissue,
renewal, extension or other application for any of said inventions or improvements, any and all
United States and foreign patents, utility models, and design registrations granted for any of
said inventions or improvements, and the right to claim priority based on the filing date of said
application under the International Convention for the Protection of Industrial Property, the
Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like
purposes and we authorize the Assignee to apply in all countries in our name or in its own name
for patents, utility models, design registrations and like rights of exclusion and for inventors'
certificates for said inventions and improvements; and we agree for ourselves and our
respective heirs, legal representatives and assigns, without further compensation to perform
such lawful acts and to sign such further applications, assignments, Preliminary Statements and
other lawful documents as the Assignee may reasonably request to effectuate fully this
assignment. Date: 2019-12-19 CHU, HSienshih
Date: 2019.12.19 CHU, Historia
Date: 70 (9. /2. (9 CHU, Hsienshit: HUANG, Dehao.
Date: 2019. 17.19 HUANG, Dehao.
CHOLL Yunfain
Date: 2019, 2.19 XU, Yaqquang XU, Yaqquang
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Date: 2019, 12,20

7 UNG, Yucheng

PATENT REEL: 057291 FRAME: 0862

RECORDED: 08/26/2021